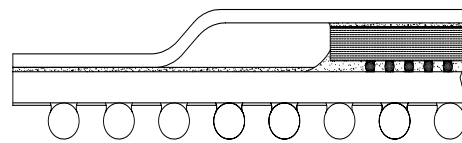


SF363 - Sn/Pb SOLDER BALLS
SFG363 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	\approx	1.79	1.99	3
A ₁	0.36	0.40	0.44	
A ₂	1.14	\approx	1.55	
D/E	17.00 BASIC			
D ₁ /E ₁	15.20 REF			
e	0.80 BASIC			
øb	0.45	0.50	0.55	3
aaa	\approx	\approx	0.20	3
bbb	\approx	\approx	0.25	3
ccc	\approx	\approx	0.20	3
eee	\approx	\approx	0.25	3
fff	\approx	\approx	0.10	3
M	20			2



SECTION A-A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MO-216-BAM-1 (DEPOPULATED) EXCEPT FOR DIMENSIONS "A", "øb" AND ASSOCIATED TOLERANCES AS NOTED.

363-BALL FLIP-CHIP BGA (SF363/SFG363)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
03/28/05	1.0.1	Minor editorial updates.
03/24/08	1.1	Updated JEDEC to MO-216-BAM-1. Added the SFG package prefix and material information.
6/10/08	1.2	Redefined "A2" dimension to point to top and bottom of package. Updated "A2" dimension table and changed JEDEC reference in the notes section.